

1/9

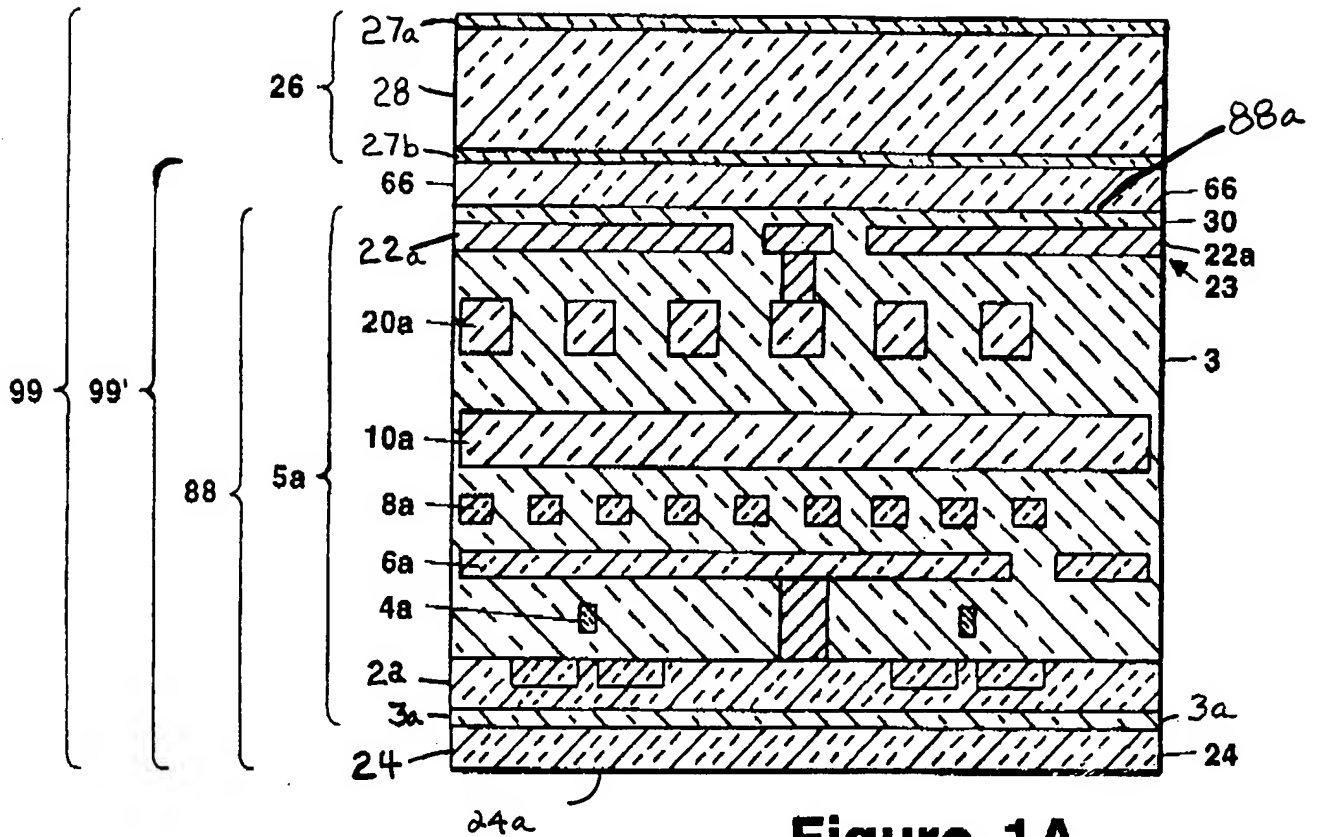


Figure 1A

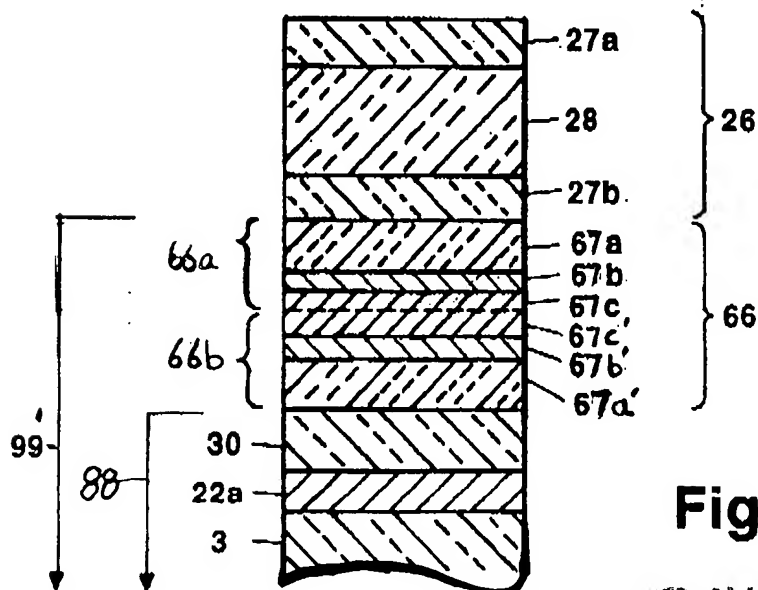


Figure 1B

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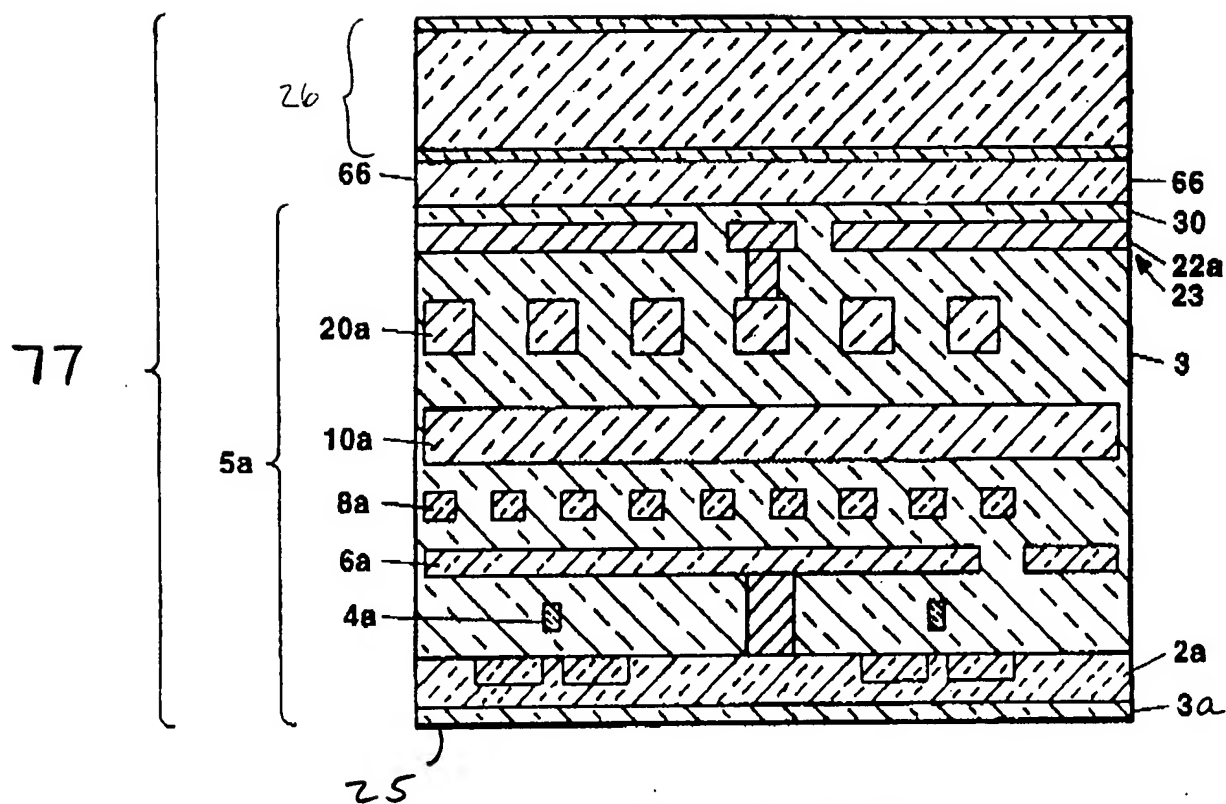


Figure 2A

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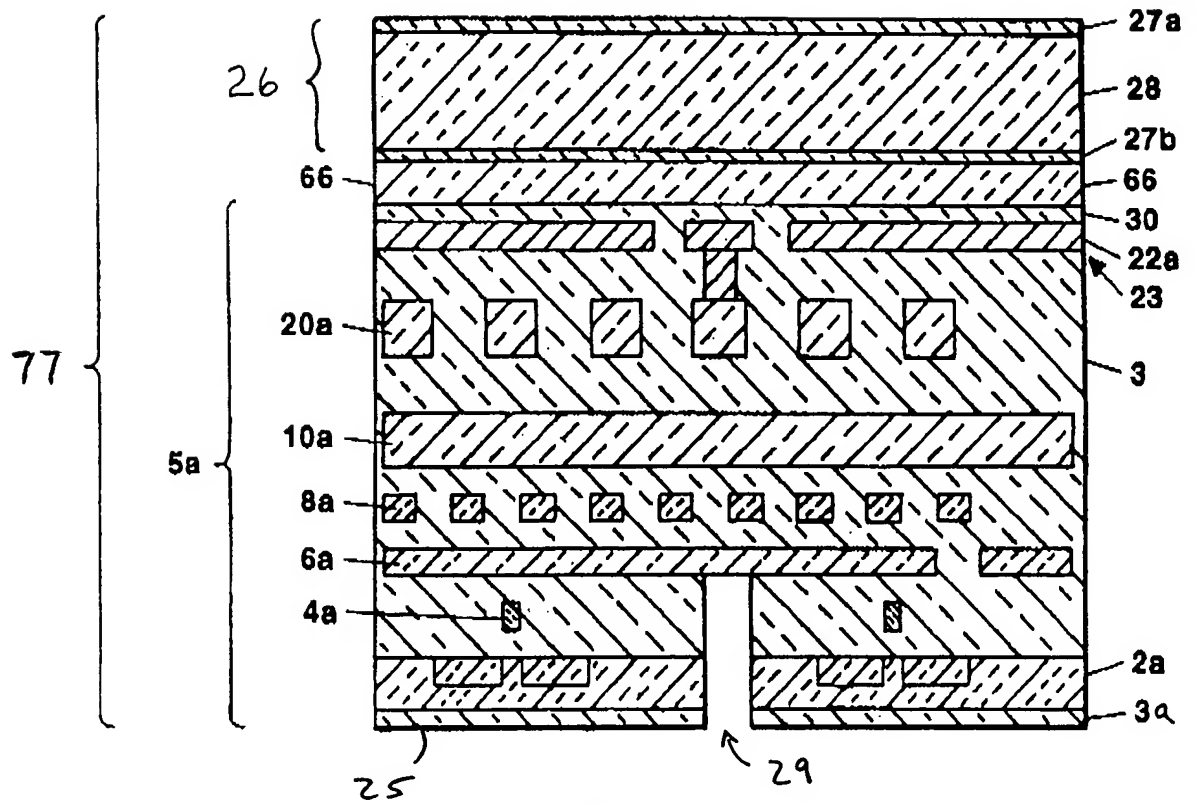


Figure 2B

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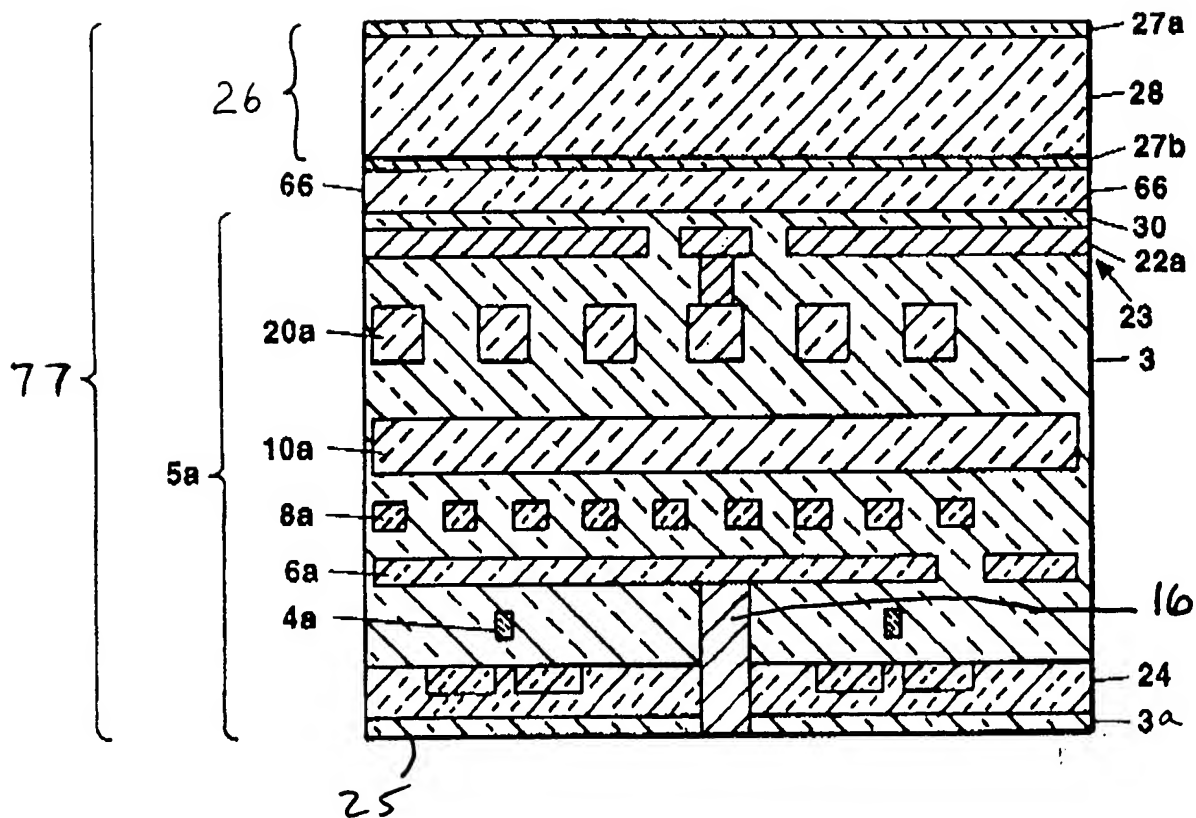
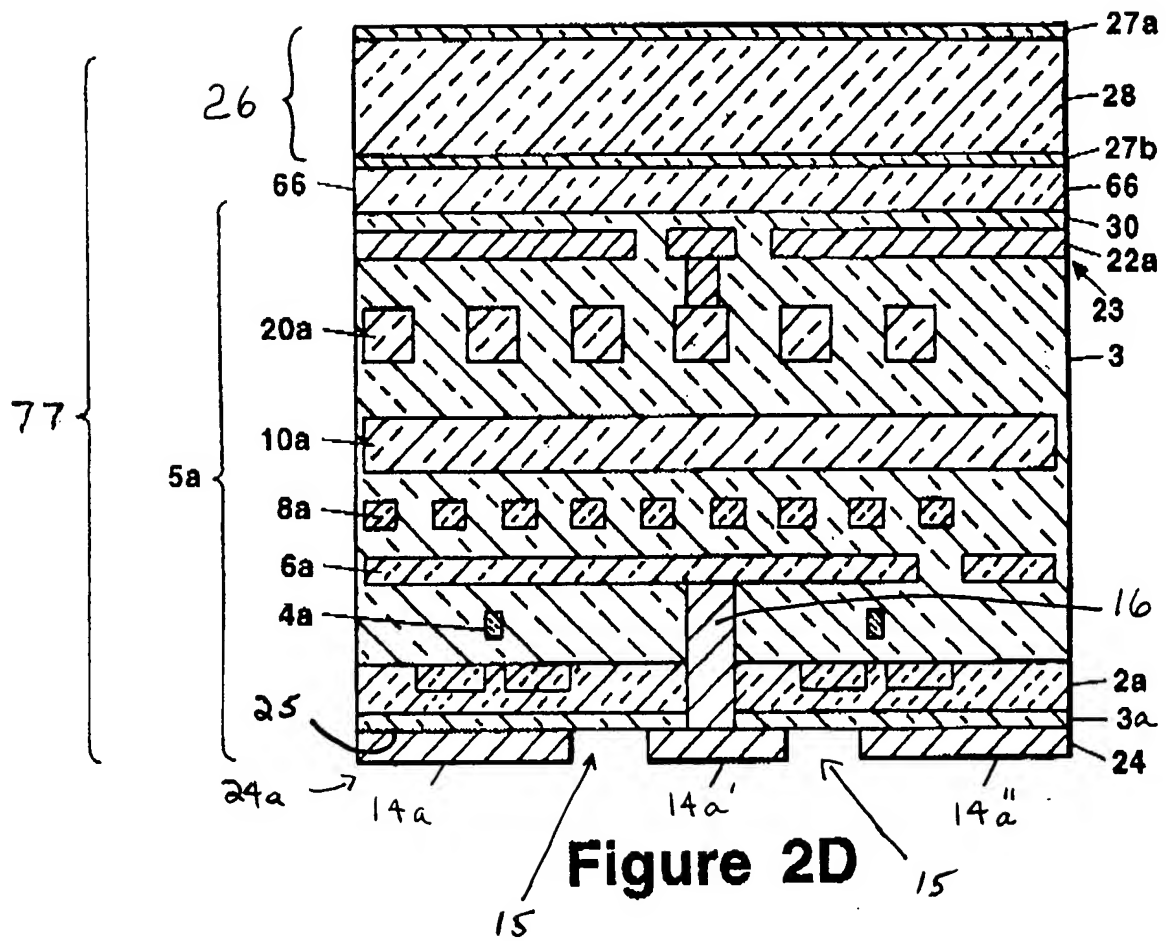


Figure 2C

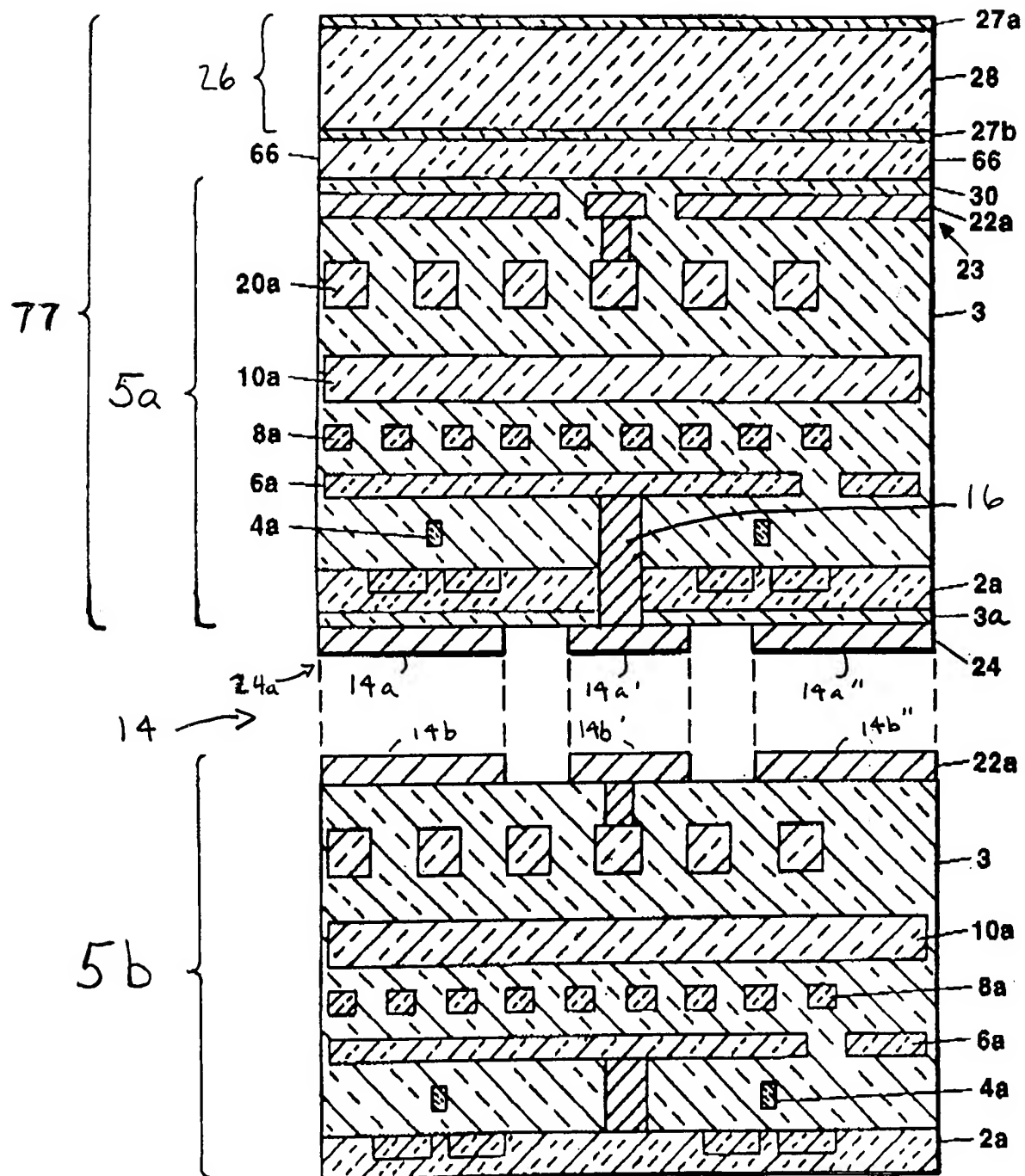
METHOD OF FORMING A MULTI-LAYER SEMICONDUCTOR STRUCTURE INCORPORATING  
A PROCESSING HANDLE MEMBER

Rafael Reif, et al.  
MIT-136BUS

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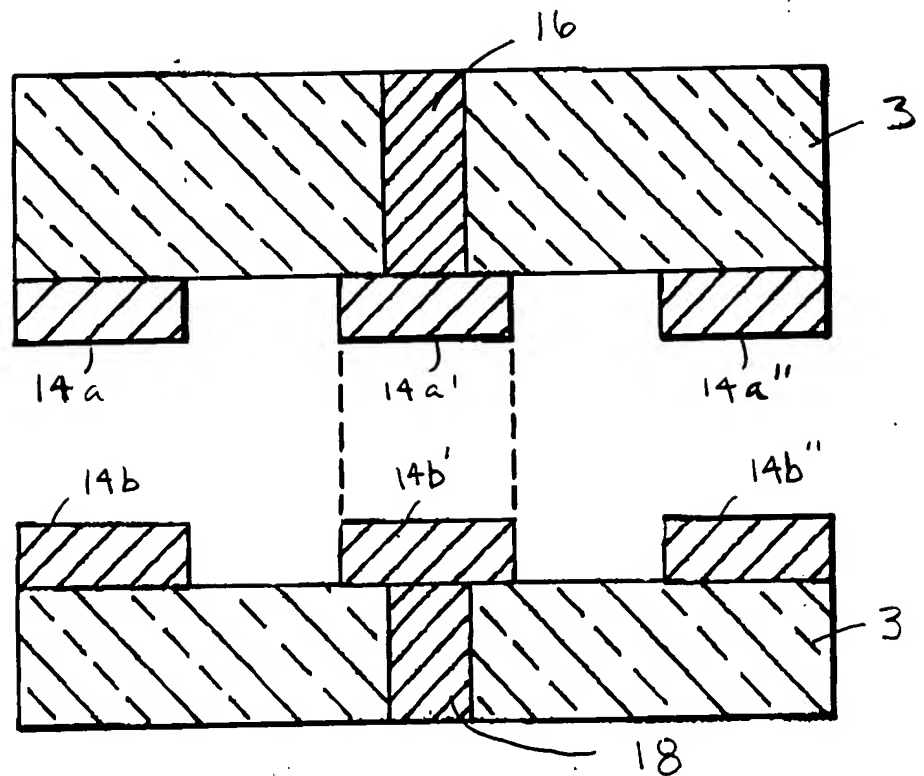


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### Figure 3A

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**Figure 3B**

METHOD OF FORMING A MULTI-LAYER SEMICONDUCTOR STRUCTURE INCORPORATING  
A PROCESSING HANDLE MEMBER

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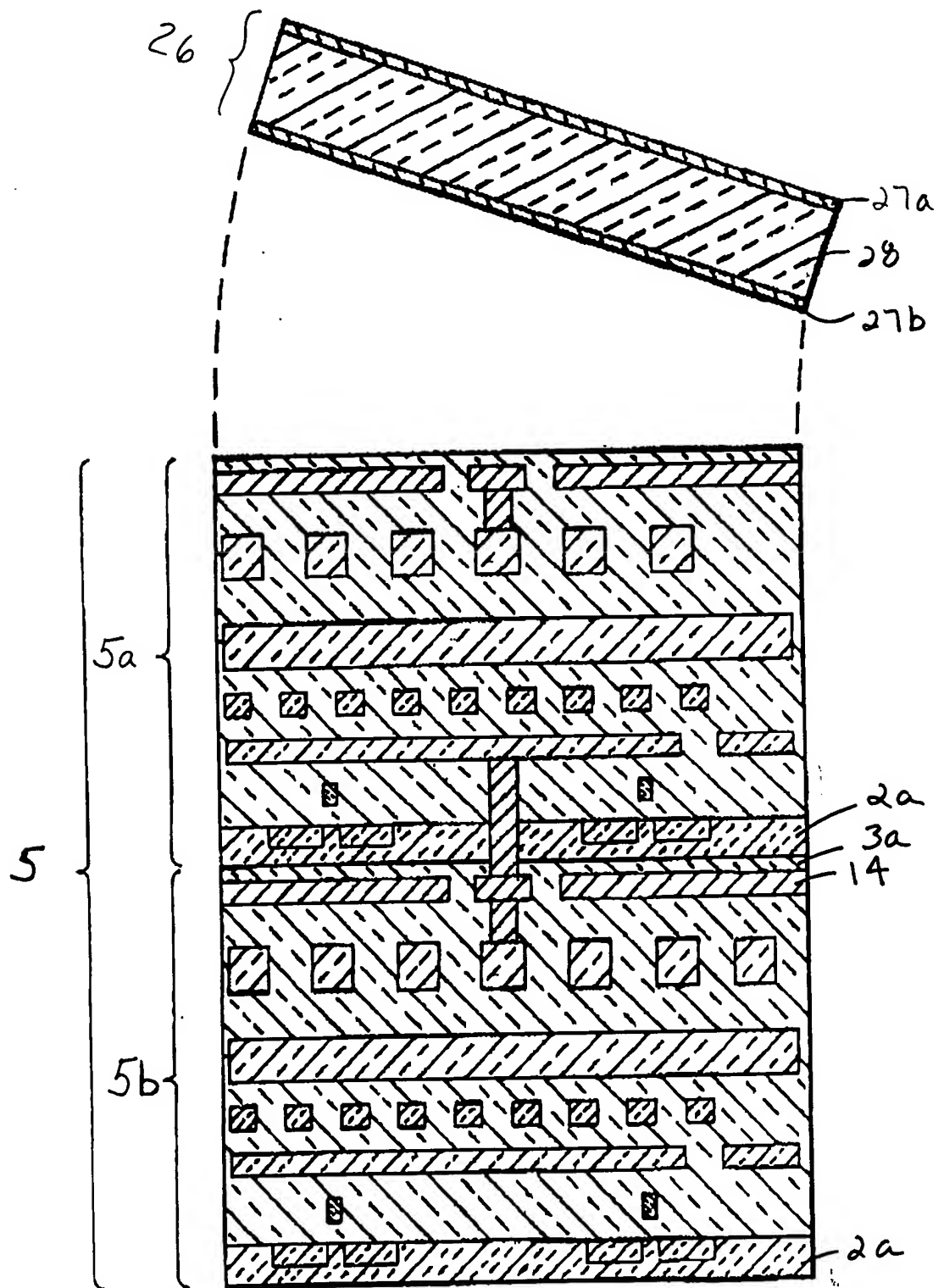


Figure 4A



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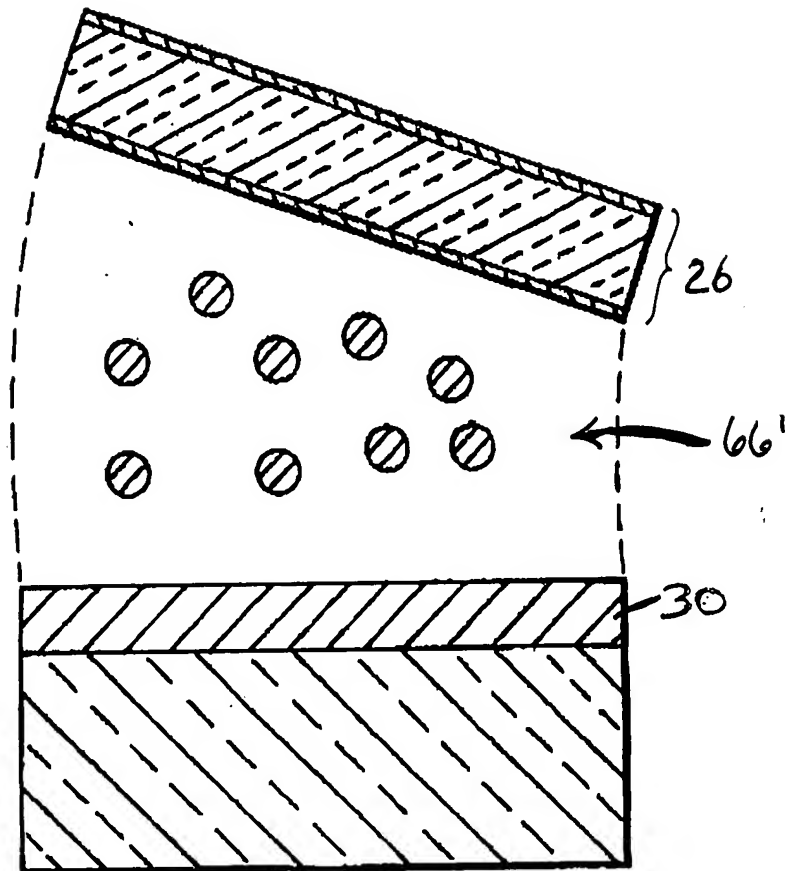


Figure 4B